

Docket No. 0756-2413

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT application of )  
Yasuhiko TAKEMURA et al. )  
Serial No. 10/028,269 ) Confirmation No. 2821  
Filed: December 28, 2001 )  
For: SEMICONDUCTOR DEVICE AND )  
A MANUFACTURING METHOD FOR )  
THE SAME )

## CERTIFICATE OF MAILING

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CDM Dated

PRELIMINARY AMENDMENT

Please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claim 1 in its entirety.

Please add new claims 2-21 as follows:

2. A method for forming a semiconductor device comprising:  
forming a semiconductor film over a substrate;  
forming a first insulating film comprising silicon oxide over said semiconductor film;  
forming a gate electrode over said first insulating film;  
patterning said first insulating film into a second insulating film comprising silicon oxide;  
introducing an impurity into said semiconductor film using said gate electrode and said second insulating film as masks to form a source region and a drain



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**FACSIMILE COVER SHEET**

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Number of Pages (including cover sheet):	10		

RE: Application Serial No. 10/028,269  
Our Reference: 0756-2413

As requested.

Eric J. Robinson